

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	("20010031514").PN.	USPAT	OR	OFF	2005/01/14 15:28
L2	1	("20010031514").PN.	US-PGPUB; USPAT	OR	OFF	2005/01/14 14:57
L12	247	(chip or die) and (silicon near carrier) and (@ad<"20011231")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 16:03
L13	99	L12 and (ball or bump or balls or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:28
L14	0	(chip or die) and (silicon near cinterposer) and (@ad<"20011231")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:19
L15	60	(chip or die) and (silicon near interposer) and (@ad<"20011231")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:19
L16	52	L15 and (ball or bump or balls or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:19
L17	39	L16 and (dielctric or insulation ir insulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:20
L18	47	L16 and (dielectric or insulation or insulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:28

L19	774	257/758.ccls. and (silicon near (substrate or wafer or board or carrier or interposer)) and (@ad<"20011231")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:42
L20	728	L19 and (dielectric or insulation or insulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:44
L21	78	L20 and (ball or bump or balls or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:42
L22	154	257/759.ccls. and (silicon near (substrate or wafer or board or carrier or interposer)) and (@ad<"20011231")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:43
L23	78	L21 and (ball or bump or balls or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:44
L24	0	L23 not L21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:42
L25	615	(csp or (chip adj scale)) and (silicon near (substrate or wafer or board or carrier or interposer)) and (@ad<"20011231")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:44
L26	462	L25 and (ball or bump or balls or bumps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:44

L27	345	L26 and (dielectric or insulation or insulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 16:03
L28	345	L27 not L12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:45
L29	333	L27 not L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:45
L30	200	(wafer near packaging) and (dielectric or insulation or insulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 16:03
L31	132	L30 and (@ad<"20011231")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 16:03
S1	1	"20020074641"	US-PGPUB; USPAT	OR	OFF	2005/01/14 12:16
S2	32019	(chip or die) and (silicon near (substrate or wafer or board)) and (@ad<"20011231")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 15:23
S3	599	S2 and (csp or (chip adj scale))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 12:18
S4	509	S3 and ((chip or die) with (substrate or wafer or board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 13:28

S5	216	S4 and ((cavity or trench or via) with (substrate or wafer or board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 13:30
S6	130	S5 and ((cavity or trench or via) with (chip or die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 13:43
S7	786	soi and ((cavity or trench or via) with (chip or die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 13:43
S8	434	S7 and (@ad<"20011231")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 13:43
S9	256	S8 and (silicon near (substrate or wafer or board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 13:44
S10	246	S9 not S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/14 14:55